



Material Content Data Sheet



Sales Product Name		ICE2A165		Issued		20. July 2018		
MA#		MA001115474						
Package		PG-DIP-8-13		Weight*		557.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.846	0.87	0.87	8691	8691
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7707	
wire	non noble metal	copper	7440-50-8	174.475	31.30	32.12	312956	321144
	noble metal	gold	7440-57-5	0.185	0.03	0.03	332	332
	encapsulation	organic material	carbon black	1333-86-4	1.089	0.20		1953
encapsulation	plastics	epoxy resin	-	35.205	6.31		63147	
	inorganic material	silicondioxide	60676-86-0	326.641	58.59	65.10	585898	650998
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13445	13445
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1427	1427
glue	plastics	epoxy resin	-	0.331	0.06		594	
	noble metal	silver	7440-22-4	1.878	0.34	0.40	3369	3963
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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